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Washington, DC 20231.

Filed

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Vishnu K. Agarwal

Serial No. : 09/652,714

: August 31, 2000

Examiner

Group Art Unit

: 2815 : Jose R. Diaz

Attorney Docket No.: 501082.10 (98-0616.09

: DEVICE AND METHOD FOR PROTECTING AGAINST OXIDATION OF A Title

CONDUCTIVE LAYER IN SAID DEVICE

Box Non-Fee Amendment Commissioner of Patents Washington, DC 20231

AMENDMENT

Sir:

Please amend the above-captioned patent application as follows:

In the Specification:

Please replace the paragraph beginning at page 8, line 4, with the following rewritten paragraph:

--Still other gases include diborane (B₂H₆); phosphine (PH₃); and carbon-silicon compounds such as methylsilane (CH3SiH3) and hexamethyldisilane (CH3)3Si-Si(CH3)3; and hexamethyldisilazane (HMDS). Additional alternate embodiments of the current invention use hydrazine (N₂H₄), monomethylhydrazine, carbon tetrafluoride (CF₄), CHF₃, HCl, and boron trichloride (BCl₃), which are also useful in passivating dielectrics, as addressed in copending application 09/114,847, now issued as U.S. Patent No. 6,201,276 B1. Also included are mixtures of any of the gases or types of gases described above. Exemplary non-plasma process parameters using these other gases include a flow rate of about 2 sccm to about 400 sccm for